

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1- 2 (Cancelled)

Claim 3 (Previously Presented) A chip carrier including a dielectric or semiconductor substrate, one surface of which includes a metal-coated portion and an opposite surface of which includes a metal-coated portion, a high frequency transmission line is arranged on said one surface of the substrate and a semiconductor device is mounted on said metal-coated portion formed on said one surface of the substrate, wherein

said metal-coated portion of said one surface is connected with said metal-coated portion of said opposite surface through a metal-coated portion formed on a side surface of said substrate.

Claim 4 (Previously Presented) The chip carrier according to claim 3, wherein the metal-coated portion on the one surface of the substrate is connected with the metal-coated portion on the opposite surface by a metallic via-hole formed on passing through the substrate.

Claim 5 (Original) The chip carrier according to claim 3, wherein the metal-coated portion formed on the side surface of the substrate is formed on the side surface closest to a position at which the optical semiconductor device is mounted.

Claim 6 (Original) The chip carrier according to claim 5, wherein an area of the metal-coated portion formed on the side surface of the substrate is equal to or greater than 1/3 of the side surface.

Claims 7- 32 (Cancelled)